

## SID15N10-VB Datasheet N-Channel 100 V (D-S) MOSFET

| PRODUCT SUMMARY     |                                 |                    |  |  |
|---------------------|---------------------------------|--------------------|--|--|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)         | I <sub>D</sub> (A) |  |  |
| 100                 | 0.110 at V <sub>GS</sub> = 10 V | 15                 |  |  |
|                     | 0.115 at V <sub>GS</sub> = 6 V  | 15                 |  |  |

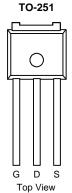
#### FEATURES

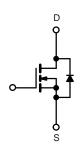
- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- 100 % R<sub>g</sub> Tested

#### **APPLICATIONS**

• Primary Side Switch







N-Channel MOSFET

| Parameter                                                       |                         | Symbol                            | Limit            | Unit |  |
|-----------------------------------------------------------------|-------------------------|-----------------------------------|------------------|------|--|
| Drain-Source Voltage                                            |                         | V <sub>DS</sub>                   | 100              |      |  |
| Gate-Source Voltage                                             | V <sub>GS</sub>         | ± 20                              | - V              |      |  |
| Continuous Drain Current (T. 175 °C)b                           | T <sub>C</sub> = 25 °C  | 1                                 | 15               |      |  |
| Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup> | T <sub>C</sub> = 125 °C | I <sub>D</sub>                    | 8.7              |      |  |
| Pulsed Drain Current                                            | I <sub>DM</sub>         | 45                                | А                |      |  |
| Continuous Source Current (Diode Conduction)                    | ۱ <sub>S</sub>          | 15                                |                  |      |  |
| Avalanche Current                                               | I <sub>AR</sub>         | 15                                | 1                |      |  |
| Repetitive Avalanche Energy (Duty Cycle $\leq$ 1 %)             | L = 0.1 mH              | E <sub>AR</sub>                   | 11.3             | mJ   |  |
| Menimum Denne Dissis stics                                      | T <sub>C</sub> = 25 °C  | P <sub>D</sub>                    | 61 <sup>b</sup>  | W    |  |
| Maximum Power Dissipation                                       | T <sub>A</sub> = 25 °C  | טי                                | 2.7 <sup>a</sup> | vv   |  |
| Operating Junction and Storage Temperature Range                |                         | T <sub>J</sub> , T <sub>stq</sub> | - 55 to 175      | °C   |  |

| THERMAL RESISTANCE RATINGS       |              |                   |         |         |      |  |
|----------------------------------|--------------|-------------------|---------|---------|------|--|
| Parameter                        |              | Symbol            | Typical | Maximum | Unit |  |
| hundting to Ambianti             | t ≤ 10 s     | R <sub>thJA</sub> | 16      | 20      | °C/W |  |
| Junction-to-Ambient <sup>a</sup> | Steady State |                   | 45      | 55      |      |  |
| Junction-to-Case                 |              | R <sub>thJC</sub> | 2       | 2.4     |      |  |

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

| <b>SPECIFICATIONS</b> ( $T_J$ = 25 °C, unless otherwise noted) |                     |                                                                                      |      |                   |       |      |  |
|----------------------------------------------------------------|---------------------|--------------------------------------------------------------------------------------|------|-------------------|-------|------|--|
| Parameter                                                      | Symbol              | Test Conditions                                                                      | Min. | Typ. <sup>a</sup> | Max.  | Unit |  |
| Static                                                         | •                   |                                                                                      |      |                   |       |      |  |
| Drain-Source Breakdown Voltage                                 | V <sub>DS</sub>     | $V_{GS} = 0 V, I_D = 250 \mu A$                                                      | 100  |                   |       | V    |  |
| Gate Threshold Voltage                                         | V <sub>GS(th)</sub> | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$                                                 | 1.0  |                   | 3.0   |      |  |
| Gate-Body Leakage                                              | I <sub>GSS</sub>    | $V_{DS} = 0 V, V_{GS} = \pm 20 V$                                                    |      |                   | ± 100 | nA   |  |
|                                                                | I <sub>DSS</sub>    | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V                                       | 1    |                   | 1     |      |  |
| Zero Gate Voltage Drain Current                                |                     | $V_{DS}$ = 100 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C                                   |      |                   | 50    | μA   |  |
|                                                                |                     | $V_{DS}$ = 100 V, $V_{GS}$ = 0 V, $T_{J}$ = 175 °C                                   |      |                   | 250   |      |  |
| On-State Drain Current <sup>b</sup>                            | I <sub>D(on)</sub>  | $V_{DS} = 5 V, V_{GS} = 10 V$                                                        | 15   |                   |       | А    |  |
|                                                                |                     | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A                                        |      | 0.110             |       | - Ω  |  |
| - · · · · · · · · · · · · · · · · · · ·                        |                     | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C               |      | 0.170             |       |      |  |
| Drain-Source On-State Resistance <sup>b</sup>                  | R <sub>DS(on)</sub> | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C               |      | 0.230             |       |      |  |
|                                                                |                     | V <sub>GS</sub> = 6 V, I <sub>D</sub> = 10 A                                         |      | 0.115             |       |      |  |
| Forward Transconductanceb                                      | 9 <sub>fs</sub>     | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A                                        |      | 25                |       | S    |  |
| Dynamic <sup>a</sup>                                           | •                   |                                                                                      |      | •                 |       |      |  |
| Input Capacitance                                              | C <sub>iss</sub>    |                                                                                      |      | 892               |       | pF   |  |
| Output Capacitance                                             | C <sub>oss</sub>    | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz                             |      | 110               |       |      |  |
| Reverse Transfer Capacitance                                   | C <sub>rss</sub>    |                                                                                      |      | 70                |       |      |  |
| Total Gate Charge <sup>c</sup>                                 | Qg                  |                                                                                      |      | 20                | 25    |      |  |
| Gate-Source Charge <sup>c</sup>                                | Q <sub>gs</sub>     | $V_{DS} = 75 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 15 \text{ A}$ |      | 5.5               |       | nC   |  |
| Gate-Drain Charge <sup>c</sup>                                 | Q <sub>gd</sub>     |                                                                                      |      | 7                 |       | 1    |  |
| Gate Resistance                                                | Rg                  |                                                                                      | 1    |                   | 3.2   | Ω    |  |
| Turn-On Delay Time <sup>c</sup>                                | t <sub>d(on)</sub>  |                                                                                      |      | 8                 | 12    |      |  |
| Rise Time <sup>c</sup>                                         | t <sub>r</sub>      | $V_{DD}$ = 75 V, $R_L$ = 5 $\Omega$                                                  |      | 35                | 55    | ns   |  |
| Turn-Off Delay Time <sup>c</sup>                               | t <sub>d(off)</sub> | $I_D \cong 15 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.5 \Omega$                   |      | 17                | 25    |      |  |
| Fall Time <sup>c</sup>                                         | t <sub>f</sub>      |                                                                                      |      | 30                | 45    |      |  |
| Source-Drain Diode Ratings and Cha                             | racteristic (T      | <sup>7</sup> <sub>C</sub> = 25 °C)                                                   |      |                   |       |      |  |
| Pulsed Current                                                 | I <sub>SM</sub>     |                                                                                      |      |                   | 45    | А    |  |
| Diode Forward Voltage <sup>b</sup>                             | V <sub>SD</sub>     | $I_{F} = 15 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$                                 |      | 0.9               | 1.5   | V    |  |
| Source-Drain Reverse Recovery Time                             | t <sub>rr</sub>     | I <sub>F</sub> = 15 A, dl/dt = 100 A/μs                                              |      | 55                | 85    | ns   |  |

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. Independent of operating temperature.

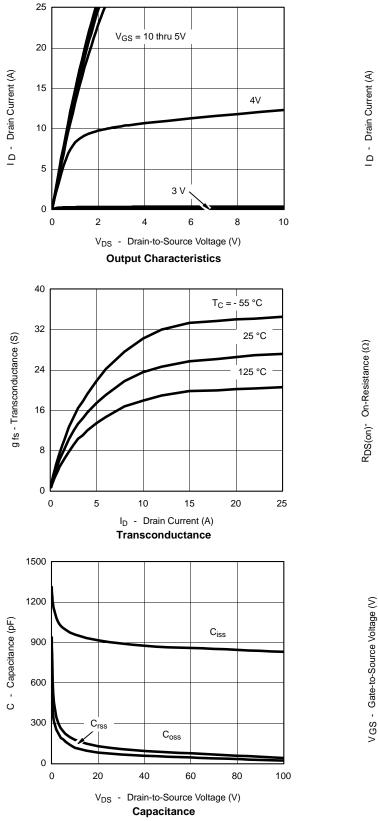
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

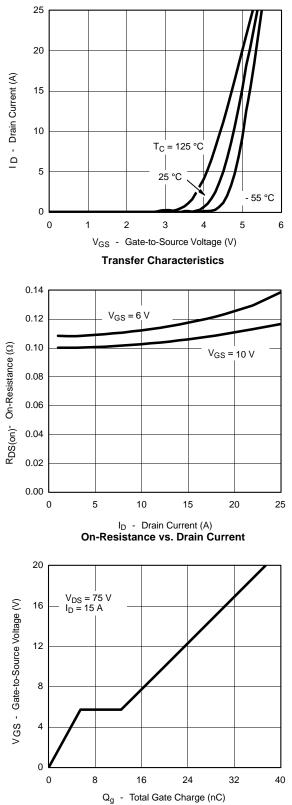
semi

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#### TYPICAL CHARACTERISTICS (25 °C unless noted)

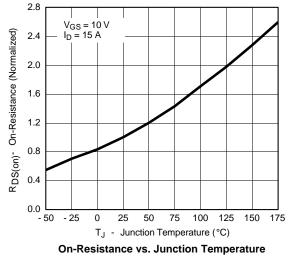




**Gate Charge** 



#### TYPICAL CHARACTERISTICS (25 °C unless noted)



**THERMAL RATINGS** 

2

1

0.1

0.01

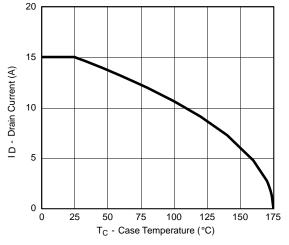
10-4

Normalized Effective Transient Thermal Impedance Duty Cycle = 0.5

0.02

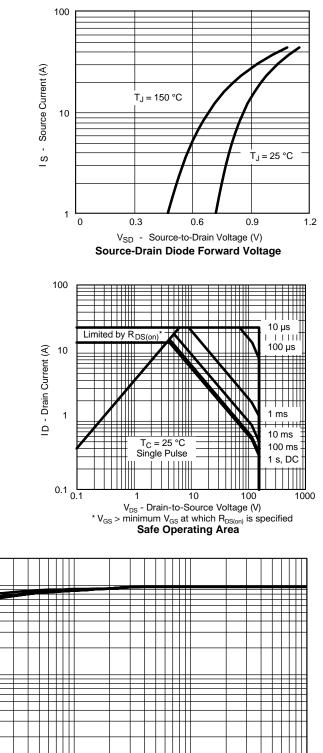
0.05 0.05 Single Pulse

0.2 0.1



Maximum Avalanche Drain Current vs. Case Temperature

10<sup>-3</sup>

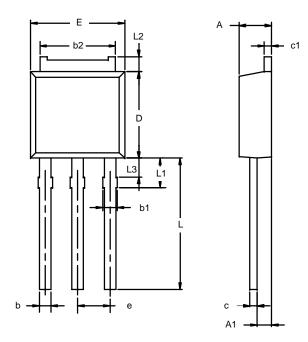


1

10<sup>-2</sup> 10<sup>-1</sup> Square Wave Pulse Duration (sec) Normalized Thermal Transient Impedance, Junction-to-Case 10



### TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

|                     | MILLIN            | IETERS      | INC       | HES   |  |
|---------------------|-------------------|-------------|-----------|-------|--|
| Dim                 | Min               | Max         | Min       | Max   |  |
| Α                   | 2.21              | 2.38        | 0.087     | 0.094 |  |
| A1                  | 0.89              | 1.14        | 0.035     | 0.045 |  |
| b                   | 0.71              | 0.89        | 0.028     | 0.035 |  |
| b1                  | 0.76              | 1.14        | 0.030     | 0.045 |  |
| b2                  | 5.23              | 5.43        | 0.206     | 0.214 |  |
| С                   | 0.46              | 0.58        | 0.018     | 0.023 |  |
| c1                  | 0.46              | 0.58        | 0.018     | 0.023 |  |
| D                   | 5.97              | 6.22        | 0.235     | 0.245 |  |
| Е                   | 6.48              | 6.73        | 0.255     | 0.265 |  |
| е                   | 2.28              | BSC         | 0.090 BSC |       |  |
| L                   | 8.89              | 9.53        | 0.350     | 0.375 |  |
| L1                  | 1.91              | 2.28        | 0.075     | 0.090 |  |
| L2                  | 0.89              | 1.27        | 0.035     | 0.050 |  |
| L3                  | 1.15              | 1.52        | 0.045     | 0.060 |  |
| ECN: S-0<br>DWG: 53 | 3946—Rev. E<br>46 | , 09-Jul-01 |           | ·     |  |



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